



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Trivedi et al.

Serial No.: 10/000,479

Filed: October 24, 2001

For: LOCAL INTERCONNECT
STRUCTURE FOR INTEGRATED
CIRCUIT DEVICES, SOURCE
STRUCTURE FOR THE SAME, AND
METHOD FOR FABRICATING THE
SAME

Confirmation No.: 4131

Examiner: T. Nguyen

Group Art Unit: 2813

Attorney Docket No.: 2269-3439.4US
(97-0936.03/US)

PATENT

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7/24/03

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

February 3, 2003
Date

Signature

Joseph A. Walkowski
Name (Type/Print)

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Box Non-Fee Amendment
Commissioner for Patents
Washington, D.C. 20231

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO-1449 be considered by the Examiner and made of record. Copies of the listed documents are enclosed pursuant to 37 C.F.R.

Serial No. «Patent Application No»

§ 1.98(a). The listed documents were cited by the Office in co-pending application Serial No. 09/999,557, filed on October 19, 2001, and directed to a related invention.

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicants herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

U.S. Patent Documents

<u>U.S. Patent No.</u>	<u>Publication Date</u>	<u>Patentee</u>
US - 4,753,851	06/1988	Roberts et al.
US - 5,196,360	03/1993	Doan et al.

Foreign Patent Documents

<u>Document No.</u>	<u>Publication Date</u>	<u>Patentee</u>
JP 5-152449	06/1993	Tomoya Baba

Applicants offer to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

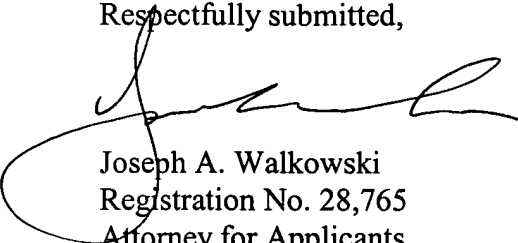
This Supplemental Information Disclosure Statement is filed after the mailing date of the first Office Action on the merits.

I hereby certify that no item of information contained in the Supplemental Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned after making reasonable

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inquiry, was known to any individual designated in 37 C.F.R. § 1.56(c) more than three months prior to the filing of the statement, and therefore no fee is due.

Respectfully submitted,



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JAW/dlm:ljb

Enclosures: Form PTO-1449 or PTO/SB/08
Copy of documents cited

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Burden Hour Statement: This form is estimated to take 2.0 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. **DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO:** Commissioner for Patents, Washington, DC 20231.